

**Thin film soldered SAM on water cooled copper heat sink
with 25.0 mm diameter for high power application
SAM- λ -A-25.0h-t**

SAM chip area	standard:	4mm x 4mm
Chip thickness	standard:	450 μ m
Front side protection	the SAM is protected with a dielectric front layer.	

The SAM chip is thin film soldered on a gold plated water cooled copper heat sink with 25.0 mm \varnothing with In thin film solder. The SAM chip is back side polished and covered with a sputter deposited Ti/Au thin film to ensure a low thermal resistance of ~ 1 K/W to the water cooled copper heat sink.

- The **standard** position of the SAM is at the centre of the heat sink.
- **Optional** the SAM can be mounted on the edge of the heat sink without extra charges.

Centre mounted SAM



Edge mounted SAM



Back side



This water cooled heat sink comes with two 1 m long water tubes with an inner diameter of 3 mm.

